

PRELIMINARY SPEC

Part Number: KPHBM-2012SURKCGKC

Hyper Red
Green

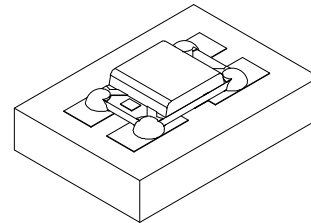
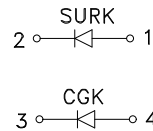
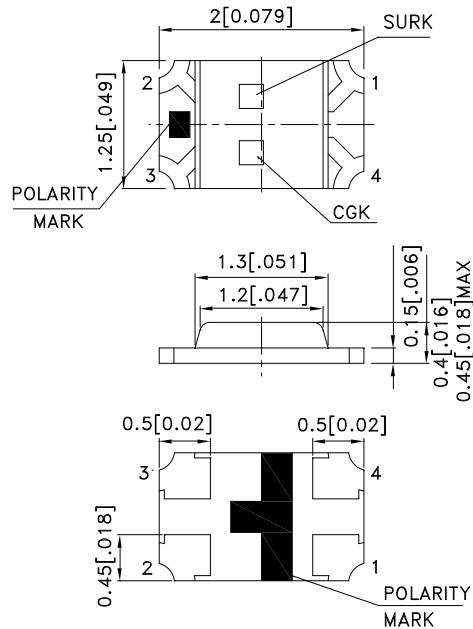
Features

- 2.0mmx1.25mm SMT LED, 0.45mm MAX. THICKNESS.
- BI -COLOR, LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with InGaAlP on GaAs substrate Light Emitting Diode.
The Green source color devices are made with InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KPHBM-2012SURKCGKC	Hyper Red (InGaAlP)	WATER CLEAR	70	200	120°
	Green (InGaAlP)		36	80	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	650 574		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red Green	635 570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20		nm	IF=20mA
C	Capacitance	Hyper Red Green	35 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	IF=20mA
IR	Reverse Current	Hyper Red Green		10 10	uA	VR = 5V

Notes:

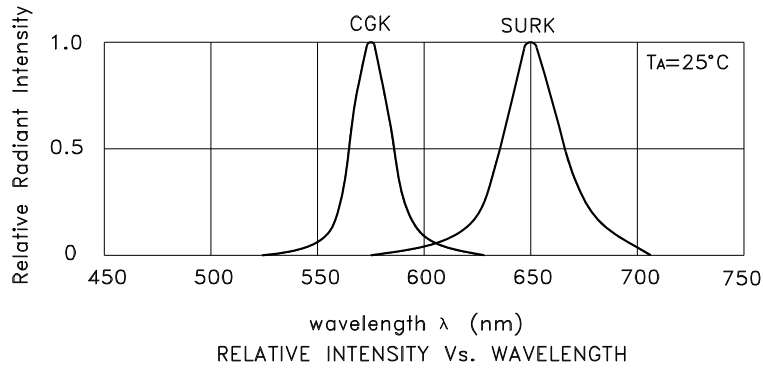
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

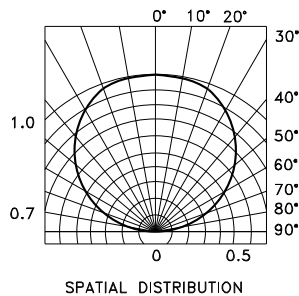
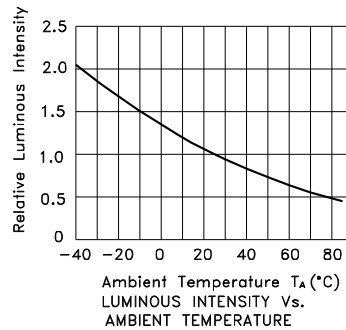
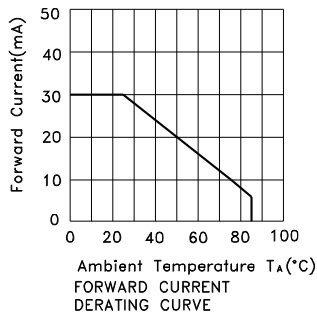
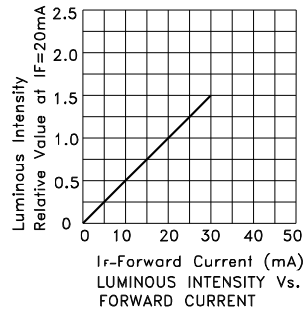
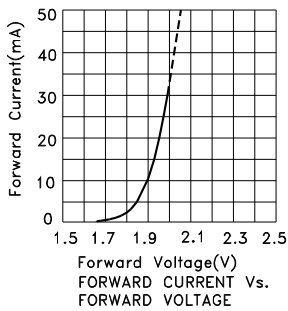
Parameter	Hyper Red	Green	Units
Power dissipation	75	75	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	150	mA
Reverse Voltage	5		V
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

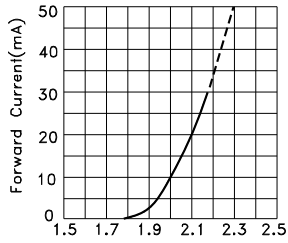
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



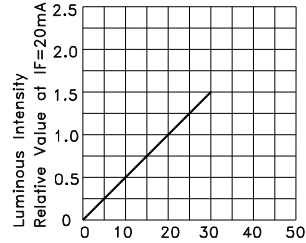
KPHBM-2012SURKCGKC Hyper Red



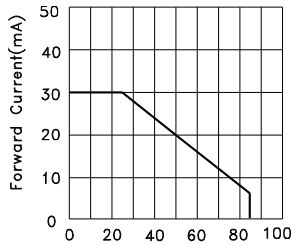
Green



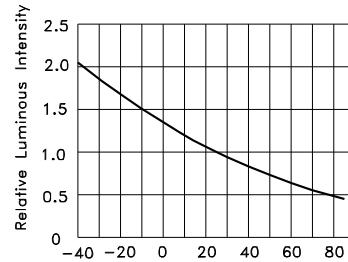
Forward Voltage(V)
FORWARD CURRENT Vs.
FORWARD VOLTAGE



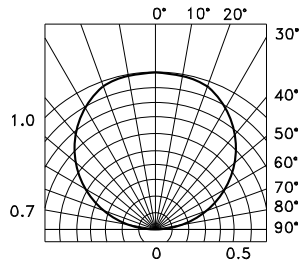
If-Forward Current (mA)
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



Ambient Temperature T_A (°C)
FORWARD CURRENT
DERATING CURVE



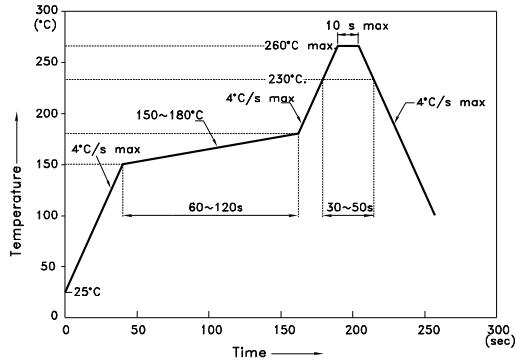
Ambient Temperature T_A (°C)
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

KPHBM-2012SURKCGKC

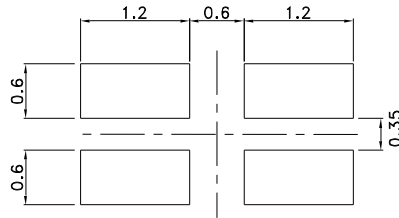
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Tape Specifications (Units : mm)

